AMENDMENTS TO THE CLAIMS

1.   (Currently Amended) A package for a rectangular integrated circuit, comprising:

a frame ~~type package,~~ having a top ~~portion,~~ surface and a bottom ~~portion~~ surface, ~~which defines at least one~~ said bottom surface including an indented area where a thickness between the top ~~portion~~ surface and the bottom ~~portion~~ surface is thinner than in a non indented area of said bottom surface, said indented area sized to accept a rectangular integrated circuit; and

~~under a thinned portion of said indented area, and said frame type package including~~ a contact portion, said contact portion extending along ~~at least~~ said bottom ~~portion and~~ surface within said indented area, and along said bottom surface within said non indented area, said contact portion being adapted to connect to said rectangular integrated circuit ~~around~~ at an edge thereof.

2.   (Original) A package as in claim 1, wherein said package includes a connection portion, adapted for soldering to said integrated circuit.

3.   (Original) A package as in claim 2, wherein said integrated circuit includes an image sensor, and a central portion of said frame defines a portion where image light can enter said image sensor.

4.   (Previously Presented) A package as in claim 1, further comprising an element which allows sealing said integrated circuit relative to an environment of said package.

5.   (Original) A package as in claim 3, further comprising a clear sealing element which allows sealing said integrated circuit relative to the environment.

6.   (Original) A package as in claim 5, wherein said clear sealing element includes a glass lid.

7.   (Original) A package as in claim 4, wherein said sealing element includes a lid portion on a top of the die and a backing portion on a rear portion of the die.

8.   (Original) A package as in claim 7, wherein said indented area includes two separate sized indented areas, one sized to receive said die, and another sized to receive said backing portion.

9.   (Original) A package as in claim 5, further comprising an element which protects said sealing element against damage.

10.   (Original) A package as in claim 9, wherein said element which protects includes an extending part which extends above a top of said sealing element.

11.   (Original) A package as in claim 3, further comprising an upper portion on said package, having surfaces adapted to accept a lens therein.

12.   (Original) A package as in claim 11, wherein said surfaces include screw threads.

13.   (Currently Amended) A package for an integrated circuit, comprising:

a packaging portion[[,]] having a first bottom surface with an outer perimeter with a metal contact portion thereon, and an inner perimeter, said inner perimeter formed by a downward facing surface with being disposed at an intersection of said first bottom surface with an inward facing surface, said packaging portion having a second bottom surface within said inner perimeter, said first bottom surface, said inward facing surface, and said second bottom surface mutually having a metal contact thereon, said metal contact being adapted to connect to an integrated circuit disposed

within said inward facing surface ~~and a bottom and sideward facing surface also having said metal contact portion thereon, said contact portion extending from said outer perimeter to said downward facing surface~~.

14.   (Original) A package as in claim 13, further comprising an element which seals an inside of said package as compared with an outside.

15.   (Original) A package as in claim 14, wherein said element which seals is transparent.

16.   (Original) A package as in claim 15, wherein said element is formed of glass, and is hermetically sealed around an area of said inner perimeter.

17.   (Previously Presented) A package as in claim 16, further comprising a backing area, hermetically sealing a bottom portion, and wherein said metal contact is disposed around said bottom portion.